

Electronic Acknowledgement Receipt

EFS ID:	8698998
Application Number:	09523990
International Application Number:	
Confirmation Number:	6138
Title of Invention:	Method of manufacture and indentification of semiconductor chip marked for identification with internal marking indicia and protection thereof by non-black layer and device produced thereby
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Ashley Campbell
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0026
Receipt Date:	25-OCT-2010
Filing Date:	13-MAR-2000
Time Stamp:	20:53:30
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$ 940
RAM confirmation Number	9701
Deposit Account	502624
Authorized User	

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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Transmittal Letter	085027_0026_tm.pdf	22225	no	1
			35af365034e2bb8d80f044dc6300286725eb1ef5		

Warnings:

Information:

2	Request for Continued Examination (RCE)	085027_0026_rce.pdf	37324	no	1
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Warnings:

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Information:

3	Transmittal Letter	085027_0026_ids.pdf	23396	no	2
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Warnings:

Information:

4	Information Disclosure Statement (IDS) Filed (SB/08)	085027_0026_idslist.pdf	63696	no	3
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5	Request for Corrected Filing Receipt	085027_0026_FRrequest.pdf	24145	no	2
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Warnings:

Information:

6		085027_0026_amendment.pdf	85899	yes	12
			6ee7fb5199b64327b4d47996760df76fa58ae066		

Multipart Description/PDF files in .zip description

	Document Description	Start	End
	Amendment Submitted/Entered with Filing of CPA/RCE	1	1
	Claims	2	4

	Applicant Arguments/Remarks Made in an Amendment	5	12		
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7	NPL Documents	1.pdf	2254221	no	4
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8	NPL Documents	2.pdf	3696109	no	9
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9	NPL Documents	3.pdf	4517666	no	7
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13	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794	no	8
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33	NPL Documents	27_PDF_LIN_Post_Passivation_Technology_Presentation_for_TSMC_Tech_Symposium_2003__pdf.pdf	1277639 20556e2754a2807cec285bcc5d87f24d52717e89	no	32
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Warnings:					
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35	Fee Worksheet (PTO-875)	fee-info.pdf	32033 3a12e876aa6d8ac536754da55e9344f14c6d9c82	no	2
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Information:					
Total Files Size (in bytes):			41064693		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><u>New Applications Under 35 U.S.C. 111</u> If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><u>National Stage of an International Application under 35 U.S.C. 371</u> If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><u>New International Application Filed with the USPTO as a Receiving Office</u> If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					